

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	CHANGER

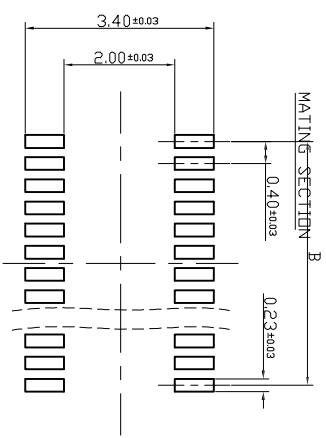
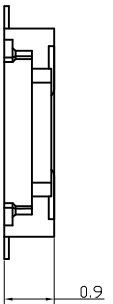
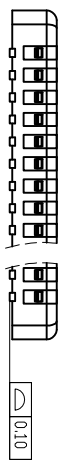
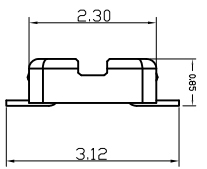
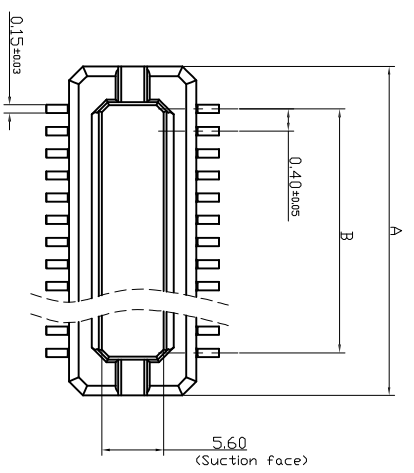


TABLE:

60	13.14	11.60
50	11.14	9.60
40	9.14	7.60
30	7.14	5.60
24	5.94	4.40
10	3.14	1.60
NUMBER OF CONTACTS	A	B

RECOMMENDED PCB LAYOUT

- Specifications:**
- Material:
 - 1-1. Molded portion: LCP resin (UL94 V-0)
 - 1-2. Contact and Post: Copper alloy.
 - Surface treatment:
 - 2-1. Terminal portion: Base: Ni plating (except the terminal tips), Exposed metal portions: Au flash plating (except the terminal tips) Or Base: Ni plating (except the terminal tips)
 - 2-2. Metal clips: Base: Ni plating Surface: Sn flash plating (except the terminal tips)
 - Characteristics:
 - 3-1. Rated voltage: 50V AC/DC
 - 3-2. Rated current: 0.3A/contact (Max. 5A at total contact)
 - 3-3. Insulation resistance: Min. 1000MΩ (initial)
 - 3-4. Breakdown voltage: 150V AC for 1 min.
 - 3-5. Saltwater spray resistance (header and socket material): 24 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ
 - 3-6. Contact resistance: Max. 90mΩ
 - 3-7. Ambient temperature: -55°C to +85°C
 - 3-8. Storage temperature: -55°C to +85°C (product only), -40°C to +50°C (emboss packing)
 - 3-9. Composite insertion force: Max. 0.981N/contact X contacts (initial)
 - 3-10. Composite removal force: Min. 0.155N/contact X contacts
 - 3-11. Post holding force: Min. 0.79N/contact
 - 3-12. Insertion and removal life: 50 times

GENERAL TOLERANCE		鉅創科技有限公司	
X±	X*± 1°	TRONTEK TECHNOLOGY CO., LTD.	
X± 0.30	X*±	TITLE: 0.40mm PITCH Board To Board 0.9H	
.XX± 0.20	.XX*±	PART NO: B0409WVM-S-XXX	
.XXX± 0.10	.XXX*±	DWG NO: 20120418	

CUSTOMER DRAWING		SCALE: 1:1		SHEET: 1 / 3	
APPROVED	CHECKED:	DRAWN:	DATE:	PROJ. NO:	REV.:
Kevin	Paul	Frank	MM		B